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Industry Leaders Develop Superspeed USB Interconnect

Popular USB Computer Connection Technology Expands Performance with Proposed USB 3.0 Specification

SAN FRANCISCO--(BUSINESS WIRE)--

Intel Corporation:

EDITOR'S NOTE: quote sheet follows press release.

Intel Corporation and other industry leaders have formed the USB 3.0 Promoter Group to create a superspeed personal USB interconnect that can deliver over 10 times the speed of today's connection. The technology, also developed by HP, Microsoft Corporation, NEC Corporation, NXP Semiconductors and Texas Instruments Incorporated, will target fast sync-and-go transfer applications in the PC, consumer and mobile segments that are necessary as digital media become ubiquitous and file sizes increase up to and beyond 25 Gigabytes.

USB (Universal Serial Bus) 3.0 will create a backward-compatible standard with the same ease-of-use and plug and play capabilities of previous USB technologies. Targeting over 10x performance increase, the technology will draw from the same architecture of wired USB. In addition, the USB 3.0 specification will be optimized for low power and improved protocol efficiency. USB 3.0 ports and cabling will be designed to enable backward compatibility as well as future-proofing for optical capabilities.

"USB 3.0 is the next logical step for the PC's most popular wired connectivity," said Jeff Ravencraft, technology strategist with Intel and president of the USB Implementers Forum (USB-IF). "The digital era requires high-speed performance and reliable connectivity to move the enormous amounts of digital content now present in everyday life. USB 3.0 will meet this challenge while maintaining the ease-of-use experience that users have come to love and expect from any USB technology."

Intel formed the USB 3.0 Promoter Group with the understanding that the USB-IF would act as the trade association for the USB 3.0 specification. A completed USB 3.0 specification is expected by the first half of 2008. USB 3.0 implementations will initially be in the form of discrete silicon.

The USB 3.0 Promoter Group is committed to preserving the existing USB device class driver infrastructure and investment, look-and-feel and ease-of-use of USB while continuing to expand this great technology's capabilities.

About the USB-IF

The non-profit USB Implementers Forum, Inc. was formed to provide a support organization and forum for the advancement and adoption of USB technology. The USB-IF facilitates the development of high-quality compatible USB devices, through its logo and compliance program and promotes the benefits of USB and the quality of products that have passed compliance testing. Further information, including postings of the most recent product and technology announcements, is available by visiting the USB-IF Web site at www.usb.org.

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Quote Sheet

Participating Company Press Quotes:
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"HP's commitment to providing customers with a reliable method for connecting peripherals is evident through our support of both USB 2.0 and Wireless USB technologies," said Phil Schultz, vice president, Consumer Inkjet Solutions, HP. "Now, with USB 3.0, we're creating an even better experience for customers when connecting their printers, digital cameras or other peripheral devices to their PCs."

"Intel worked jointly with industry leaders in the development and adoption of two generations of USB, which has become the number one peripheral interface in computing and hand-held consumer electronic devices," said Patrick Gelsinger, senior vice president and general manager, Digital Enterprise Group, Intel Corporation. "As the market evolves to support customer demands for storing and moving larger amounts of digital content, we look forward to developing the third generation of USB technology that leverages the current USB interface and optimize it to meet these demands."

"NEC has been a supporter of USB technologies since the first installment of wired USB," said Katsuhiko Itagaki, general manager, SoC Systems Division, NEC Electronics Corporation. "Now it's time to evolve an already successful interface to meet market demands for moving large amounts of content at faster speeds to minimize users wait time."

"NXP is pleased to join other top-tier companies in advancing the number one interconnect technology in the world to meet the needs of next-generation peripherals," said Pierre-Yves Couteau, director of Strategy & Business Development, Business Line Connected Entertainment, NXP Semiconductors. "As a leading provider of USB semiconductor solutions, NXP is committed to drive the standardization and applications of Superspeed USB in the industry,"

"With the proliferation of Hi-Speed USB in a wide number of market segments, including personal computing, consumer electronics, and mobility, we anticipate that USB 3.0 will rapidly become the de facto standard as the replacement of USB 2.0 ports in applications where higher bandwidth is valued," said Greg Hantak, vice president Worldwide ASIC at Texas Instruments Incorporated. "TI is excited about the new applications and improved user experience that will be enabled by the performance of USB 3.0."

Source: Intel Corporation